

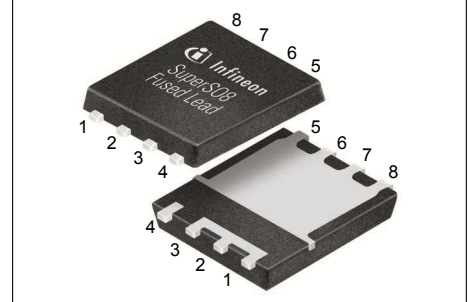
MOSFET

OptiMOS™ 5 Power-Transistor, 30 V

Features

- Monolithically integrated Schottky-like diode
- Very low on-resistance $R_{DS(on)}$ @ $V_{GS}=4.5\text{ V}$
- Optimized charges for fast switching
- Optimized QGD/QGS for induced turn on ruggedness
- 100% avalanche tested
- N-channel
- Pb-free lead plating; RoHS compliant
- Halogen-free according to IEC61249-2-21

TDSON-8 FL (enlarged source interconnection)

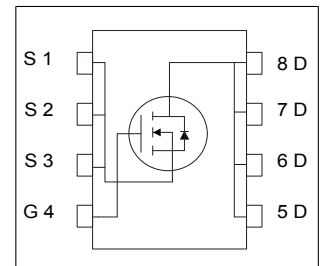


Product validation

Fully qualified according to JEDEC for Industrial Applications

Table 1 Key Performance Parameters

Parameter	Value	Unit
V_{DS}	30	V
$R_{DS(on),max}$	0.55	mΩ
I_D	433	A
Q_{oss}	81	nC
$Q_G(0V..4.5V)$	63	nC



Type / Ordering Code	Package	Marking	Related Links
BSC005N03LS5I	TDSON-8 FL	5N03LS5I	-

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1 Maximum ratings

at $T_A=25\text{ °C}$, unless otherwise specified

Table 2 Maximum ratings

Parameter	Symbol	Values			Unit	Note / Test Condition
		Min.	Typ.	Max.		
Continuous drain current ¹⁾	I_D	-	-	433 306 42	A	$V_{GS}=10\text{ V}$, $T_C=25\text{ °C}$ $V_{GS}=10\text{ V}$, $T_C=100\text{ °C}$ $V_{GS}=4.5\text{ V}$, $T_A=25\text{ °C}$, $R_{THJA}=50\text{ °C/W}^{2)}$
Pulsed drain current ³⁾	$I_{D,pulse}$	-	-	1731	A	$T_A=25\text{ °C}$
Avalanche energy, single pulse ⁴⁾	E_{AS}	-	-	430	mJ	$I_D=50\text{ A}$, $R_{GS}=25\text{ }\Omega$
Gate source voltage	V_{GS}	-20	-	20	V	-
Power dissipation	P_{tot}	-	-	188 3.0	W	$T_C=25\text{ °C}$ $T_A=25\text{ °C}$, $R_{THJA}=50\text{ °C/W}^{2)}$
Operating and storage temperature	T_j , T_{stg}	-55	-	175	°C	IEC climatic category; DIN IEC 68-1: 55/175/56

2 Thermal characteristics

Table 3 Thermal characteristics

Parameter	Symbol	Values			Unit	Note / Test Condition
		Min.	Typ.	Max.		
Thermal resistance, junction - case, bottom	R_{thJC}	-	-	0.8	°C/W	-
Thermal resistance, junction - case, top	R_{thJC}	-	-	20	°C/W	-
Device on PCB, 6 cm ² cooling area	R_{thJA}	-	-	50	°C/W	-

¹⁾ Rating refers to the product only with datasheet specified absolute maximum values, maintaining case temperature at 25°C. For higher Tcase please refer to Diagram 2. De-rating will be required based on the actual environmental conditions.

²⁾ Device on 40 mm x 40 mm x 1.5 mm epoxy PCB FR4 with 6 cm² (one layer, 70 µm thick) copper area for drain connection. PCB is vertical in still air.

³⁾ See Diagram 3 for more detailed information

⁴⁾ See Diagram 13 for more detailed information

3 Electrical characteristics

at $T_j=25\text{ °C}$, unless otherwise specified

Table 4 Static characteristics

Parameter	Symbol	Values			Unit	Note / Test Condition
		Min.	Typ.	Max.		
Drain-source breakdown voltage	$V_{(BR)DSS}$	30	-	-	V	$V_{GS}=0\text{ V}$, $I_D=1\text{ mA}$
Breakdown voltage temperature coefficient	$dV_{(BR)DSS}/dT_j$	-	15	-	mV/°C	$I_D=10\text{ mA}$, referenced to 25 °C
Gate threshold voltage	$V_{GS(th)}$	1	1.5	2	V	$V_{DS}=V_{GS}$, $I_D=10\text{ mA}$
Zero gate voltage drain current	I_{DSS}	-	-	0.5	mA	$V_{DS}=24\text{ V}$, $V_{GS}=0\text{ V}$, $T_j=25\text{ °C}$ $V_{DS}=24\text{ V}$, $V_{GS}=0\text{ V}$, $T_j=125\text{ °C}$
Gate-source leakage current	I_{GSS}	-	10	100	nA	$V_{GS}=20\text{ V}$, $V_{DS}=0\text{ V}$
Drain-source on-state resistance	$R_{DS(on)}$	-	0.51 0.68	0.55 0.95	mΩ	$V_{GS}=10\text{ V}$, $I_D=50\text{ A}$ $V_{GS}=4.5\text{ V}$, $I_D=50\text{ A}$
Gate resistance ¹⁾	R_G	-	0.7	1.2	Ω	-
Transconductance	g_{fs}	-	290	-	S	$ V_{DS} \geq 2 I_D /R_{DS(on)max}$, $I_D=50\text{ A}$

Table 5 Dynamic characteristics

Parameter	Symbol	Values			Unit	Note / Test Condition
		Min.	Typ.	Max.		
Input capacitance ¹⁾	C_{iss}	-	8000	-	pF	$V_{GS}=0\text{ V}$, $V_{DS}=15\text{ V}$, $f=1\text{ MHz}$
Output capacitance ¹⁾	C_{oss}	-	3000	-	pF	$V_{GS}=0\text{ V}$, $V_{DS}=15\text{ V}$, $f=1\text{ MHz}$
Reverse transfer capacitance ¹⁾	C_{rss}	-	400	-	pF	$V_{GS}=0\text{ V}$, $V_{DS}=15\text{ V}$, $f=1\text{ MHz}$
Turn-on delay time	$t_{d(on)}$	-	20	-	ns	$V_{DD}=15\text{ V}$, $V_{GS}=4.5\text{ V}$, $I_D=50\text{ A}$, $R_{G,ext}=1.6\text{ Ω}$
Rise time	t_r	-	23.7	-	ns	$V_{DD}=15\text{ V}$, $V_{GS}=4.5\text{ V}$, $I_D=50\text{ A}$, $R_{G,ext}=1.6\text{ Ω}$
Turn-off delay time	$t_{d(off)}$	-	38.8	-	ns	$V_{DD}=15\text{ V}$, $V_{GS}=4.5\text{ V}$, $I_D=50\text{ A}$, $R_{G,ext}=1.6\text{ Ω}$
Fall time	t_f	-	16.3	-	ns	$V_{DD}=15\text{ V}$, $V_{GS}=4.5\text{ V}$, $I_D=50\text{ A}$, $R_{G,ext}=1.6\text{ Ω}$

¹⁾ Defined by design. Not subject to production test.

Table 6 Gate charge characteristics¹⁾

Parameter	Symbol	Values			Unit	Note / Test Condition
		Min.	Typ.	Max.		
Gate to source charge	Q_{gs}	-	19	-	nC	$V_{DD}=15\text{ V}$, $I_D=50\text{ A}$, $V_{GS}=0\text{ to }4.5\text{ V}$
Gate charge at threshold	$Q_{g(th)}$	-	11	-	nC	$V_{DD}=15\text{ V}$, $I_D=50\text{ A}$, $V_{GS}=0\text{ to }4.5\text{ V}$
Gate to drain charge ²⁾	Q_{gd}	-	19	-	nC	$V_{DD}=15\text{ V}$, $I_D=50\text{ A}$, $V_{GS}=0\text{ to }4.5\text{ V}$
Switching charge	Q_{sw}	-	27	-	nC	$V_{DD}=15\text{ V}$, $I_D=50\text{ A}$, $V_{GS}=0\text{ to }4.5\text{ V}$
Gate charge total ²⁾	Q_g	-	63	-	nC	$V_{DD}=15\text{ V}$, $I_D=50\text{ A}$, $V_{GS}=0\text{ to }4.5\text{ V}$
Gate plateau voltage	$V_{plateau}$	-	2.4	-	V	$V_{DD}=15\text{ V}$, $I_D=50\text{ A}$, $V_{GS}=0\text{ to }4.5\text{ V}$
Gate charge total	Q_g	-	128	-	nC	$V_{DD}=15\text{ V}$, $I_D=50\text{ A}$, $V_{GS}=0\text{ to }10\text{ V}$
Output charge ²⁾	Q_{oss}	-	81	-	nC	$V_{DS}=15\text{ V}$, $V_{GS}=0\text{ V}$

Table 7 Reverse diode

Parameter	Symbol	Values			Unit	Note / Test Condition
		Min.	Typ.	Max.		
Diode continuous forward current	I_S	-	-	188	A	$T_C=25\text{ °C}$
Diode pulse current	$I_{S,pulse}$	-	-	1731	A	$T_C=25\text{ °C}$
Diode forward voltage	V_{SD}	-	0.71	1	V	$V_{GS}=0\text{ V}$, $I_F=50\text{ A}$, $T_j=25\text{ °C}$
Reverse recovery charge ²⁾	Q_{rr}	-	30	-	nC	$V_R=15\text{ V}$, $I_F=23\text{ A}$, $di_F/dt=400\text{ A}/\mu\text{s}$

¹⁾ See "Gate charge waveforms" for parameter definition

²⁾ Defined by design. Not subject to production test.

4 Electrical characteristics diagrams

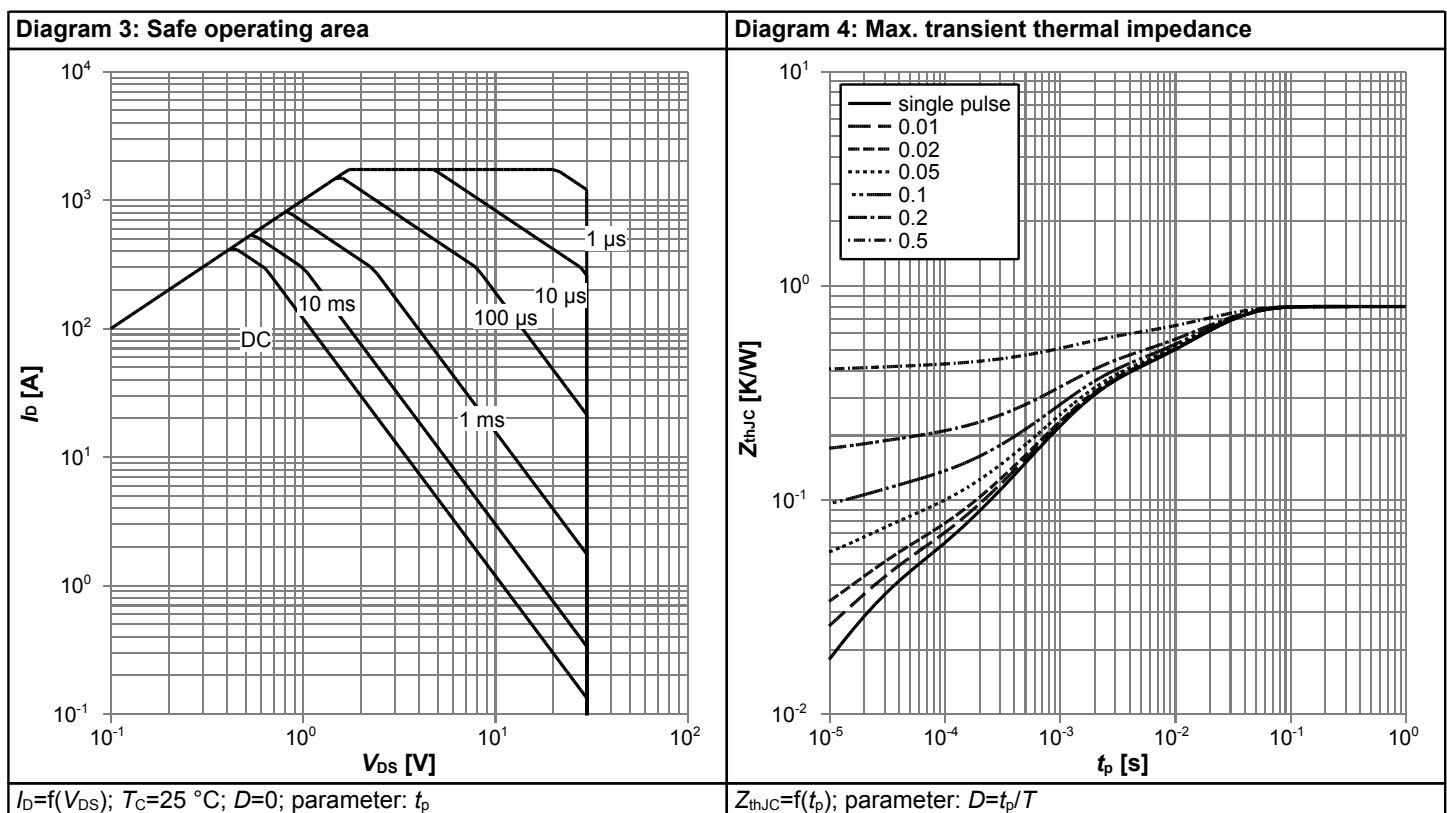
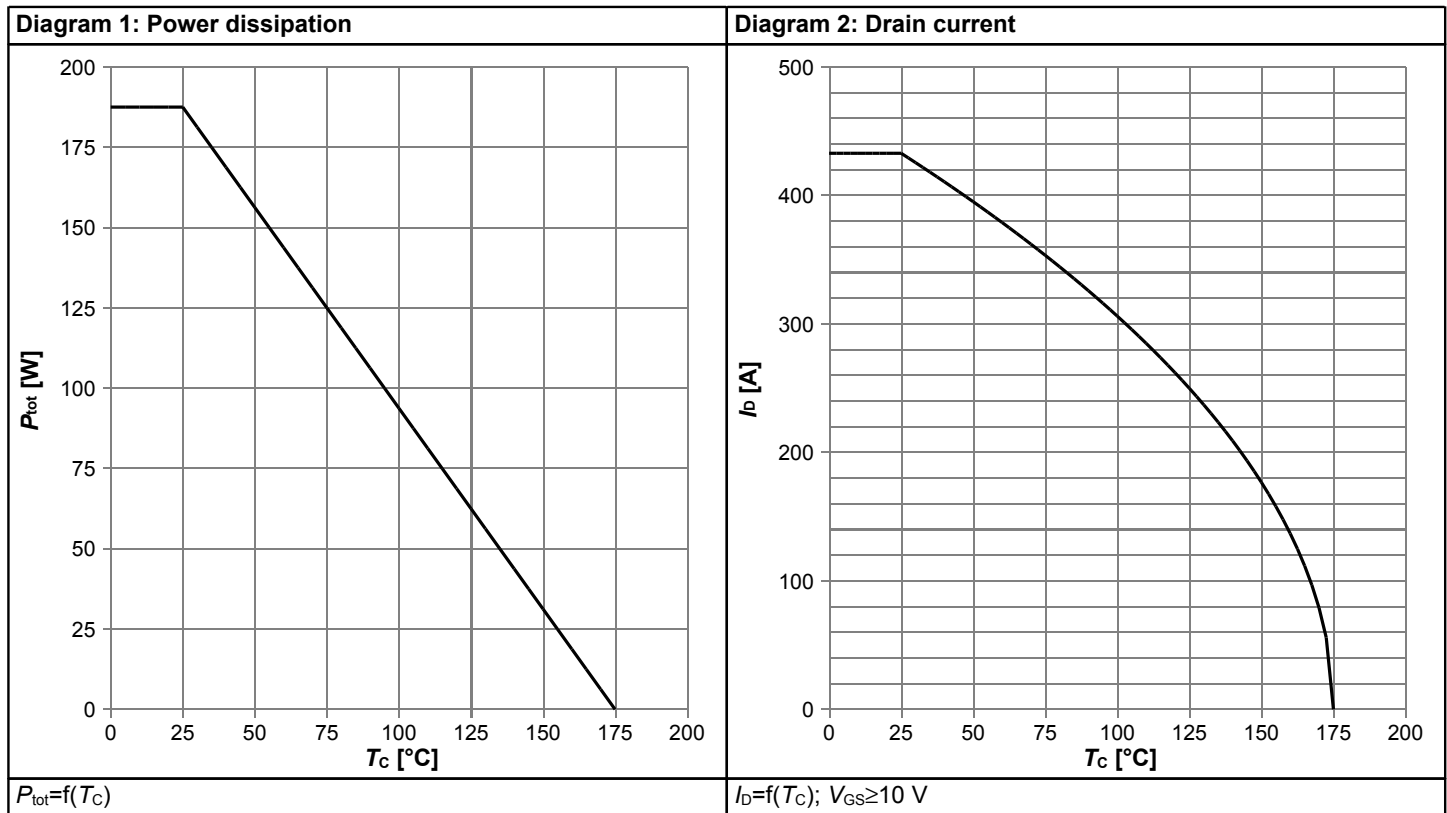
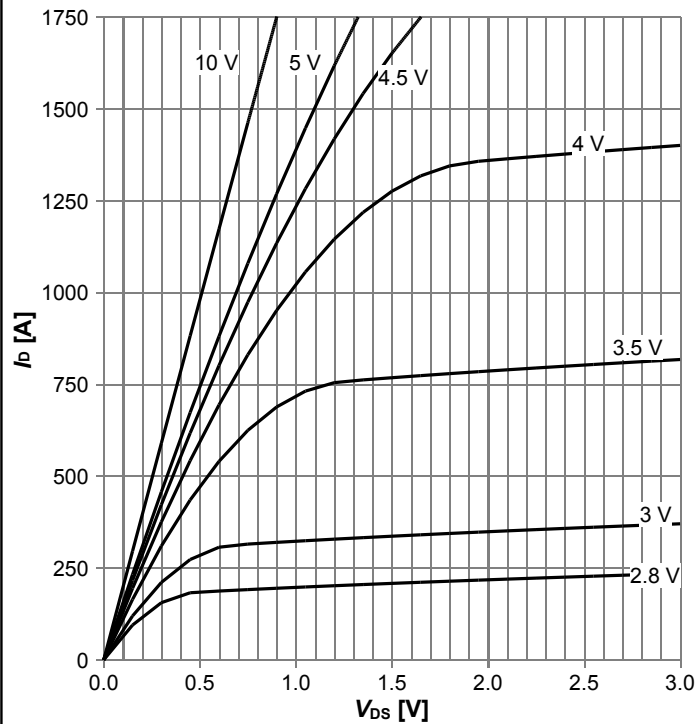
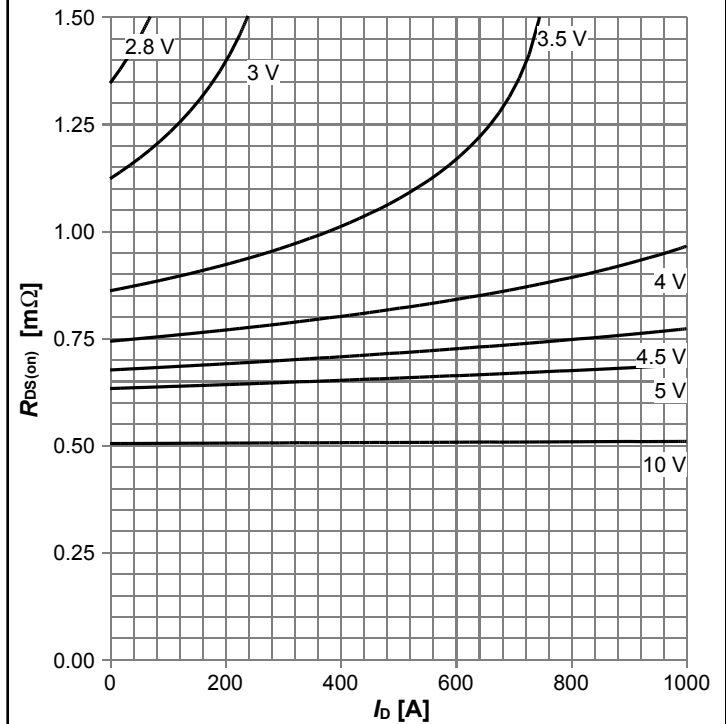


Diagram 5: Typ. output characteristics



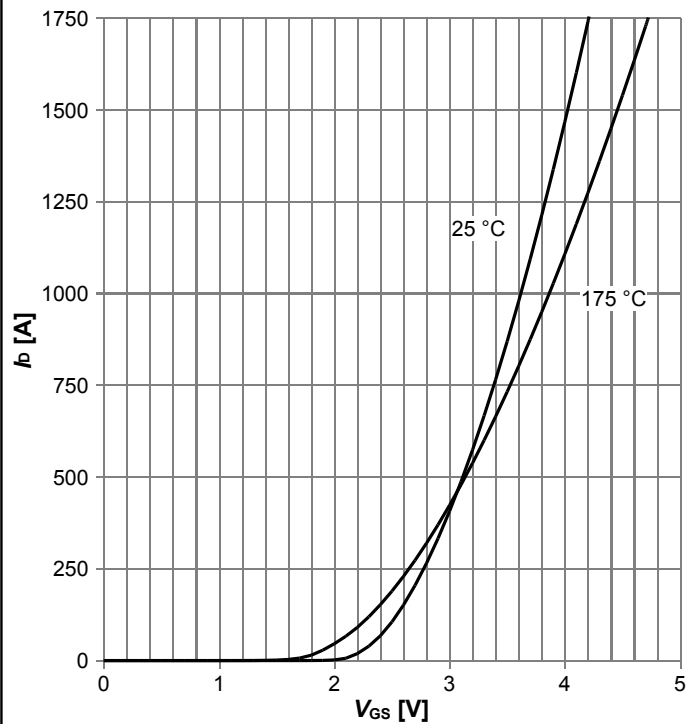
$I_D = f(V_{DS})$, $T_j = 25^\circ\text{C}$; parameter: V_{GS}

Diagram 6: Typ. drain-source on resistance



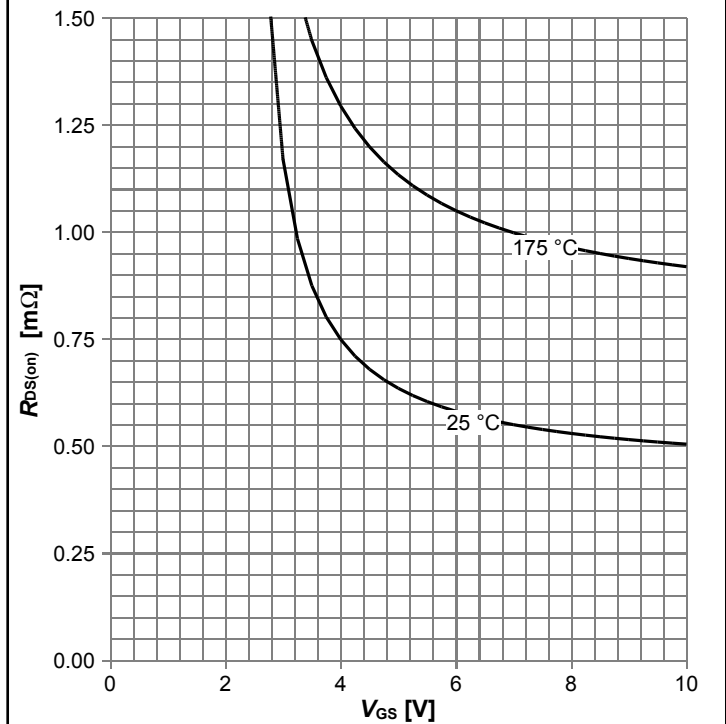
$R_{DS(on)} = f(I_D)$, $T_j = 25^\circ\text{C}$; parameter: V_{GS}

Diagram 7: Typ. transfer characteristics



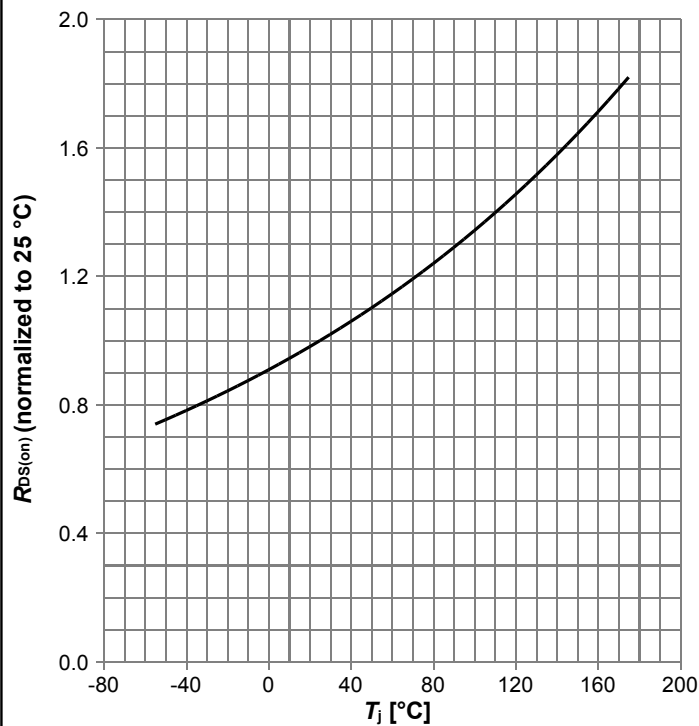
$I_D = f(V_{GS})$, $|V_{DS}| > 2|I_D|R_{DS(on)\max}$; parameter: T_j

Diagram 8: Typ. drain-source on resistance



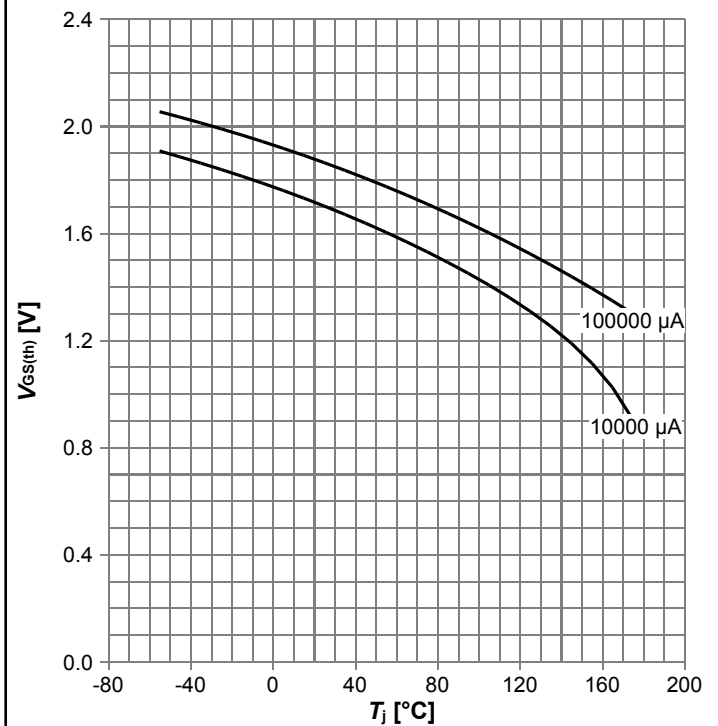
$R_{DS(on)} = f(V_{GS})$, $I_D = 50\text{ A}$; parameter: T_j

Diagram 9: Normalized drain-source on resistance



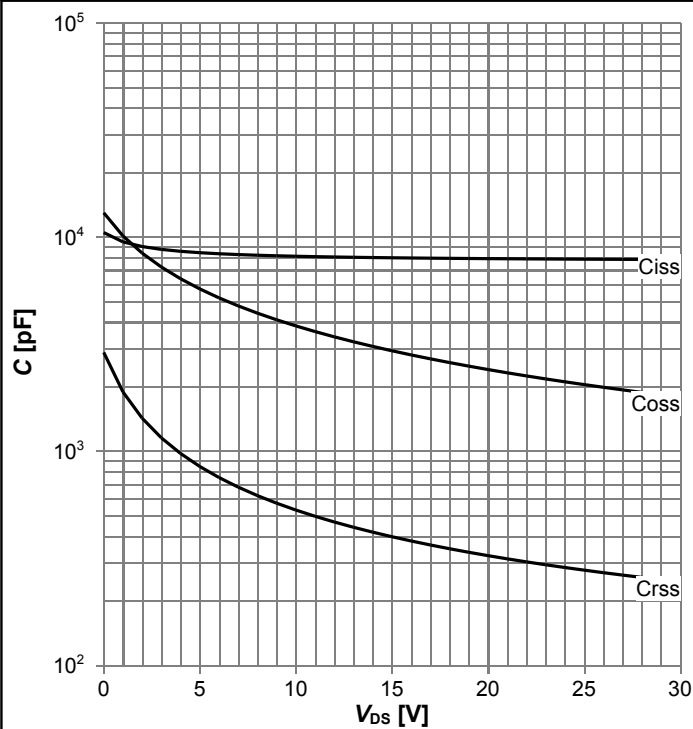
$R_{DS(on)} = f(T_j)$, $I_D = 50$ A, $V_{GS} = 10$ V

Diagram 10: Typ. gate threshold voltage



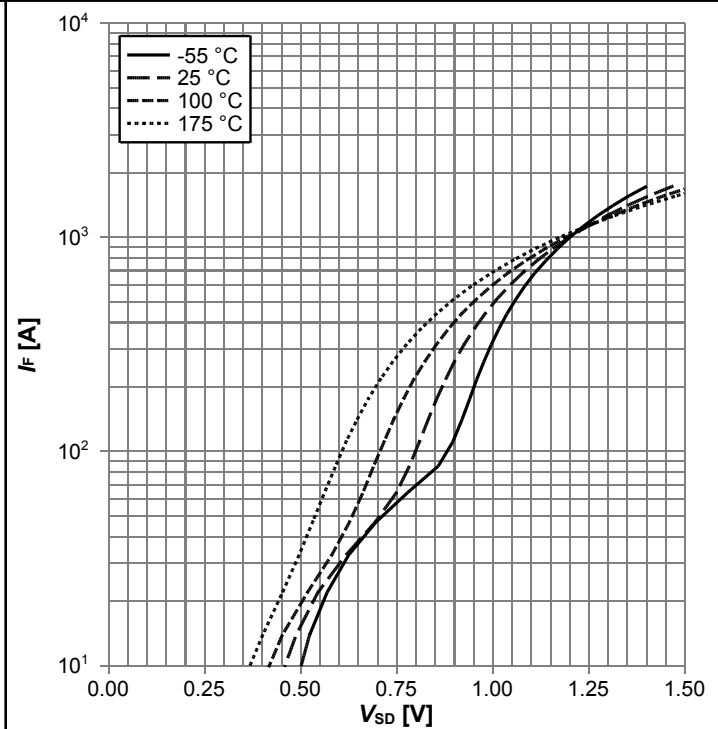
$V_{GS(th)} = f(T_j)$, $V_{GS} = V_{DS}$; parameter: I_D

Diagram 11: Typ. capacitances



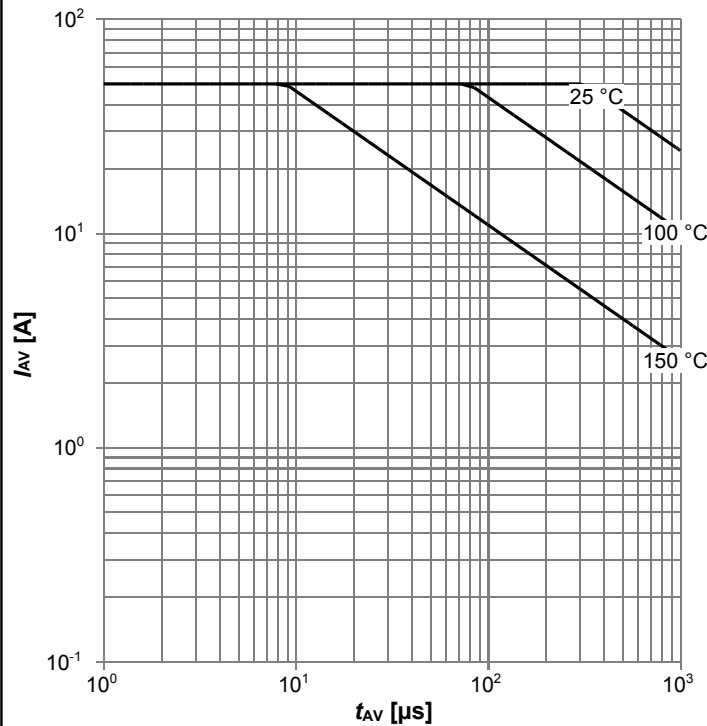
$C = f(V_{DS})$; $V_{GS} = 0$ V; $f = 1$ MHz

Diagram 12: Forward characteristics of reverse diode



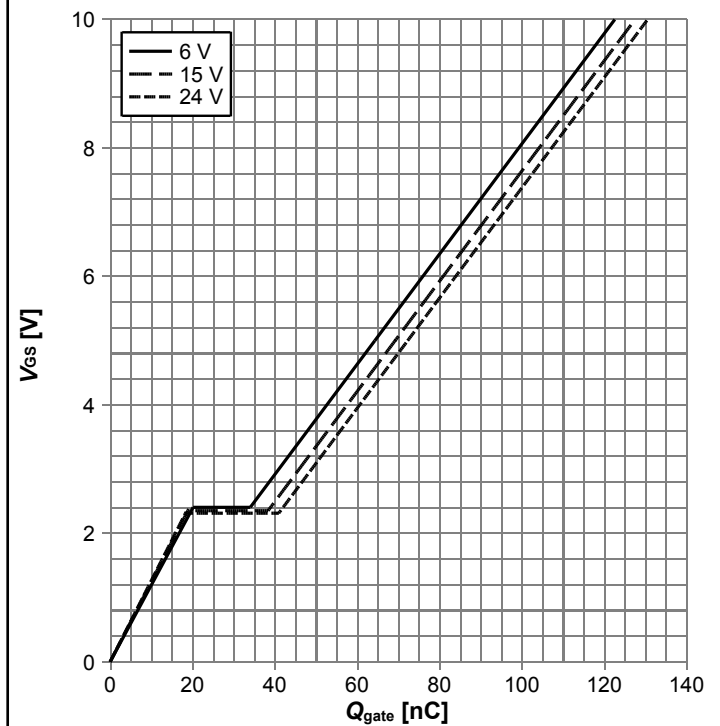
$I_F = f(V_{SD})$; parameter: T_j

Diagram 13: Avalanche characteristics



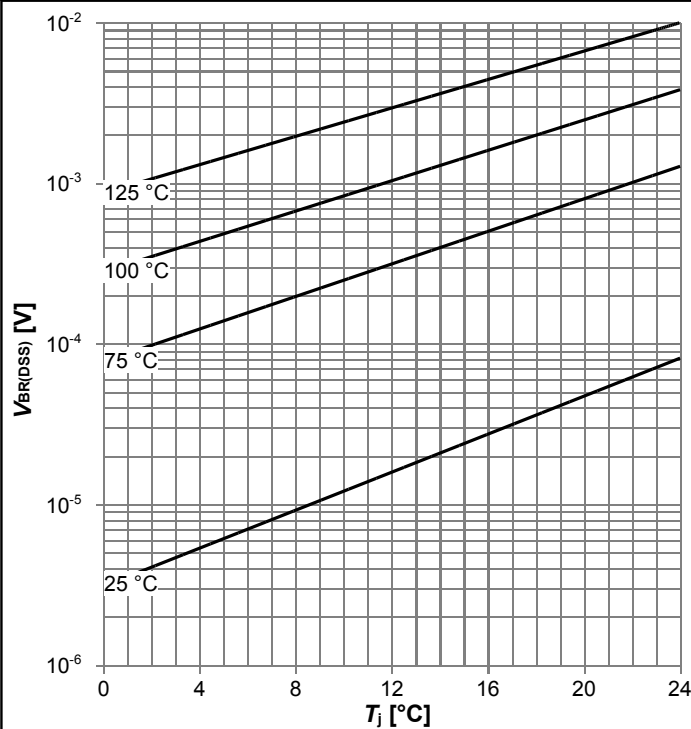
$I_{AS}=f(t_{AV})$; $R_{GS}=25\ \Omega$; parameter: $T_{j,start}$

Diagram 14: Typ. gate charge



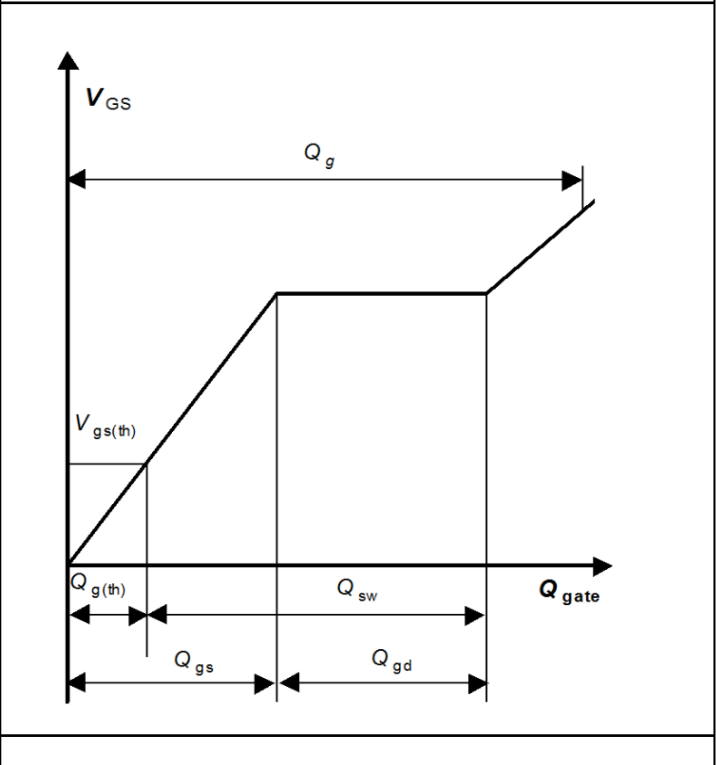
$V_{GS}=f(Q_{gate})$, $I_D=50\text{ A}$ pulsed, $T_j=25\text{ °C}$; parameter: V_{DD}

Diagram 15: Drain-source leakage current



$I_{DSS}=f(V_{DS})$, $V_{GS}=0\text{ V}$; parameter: T_j

Diagram Gate charge waveforms



5 Package Outlines

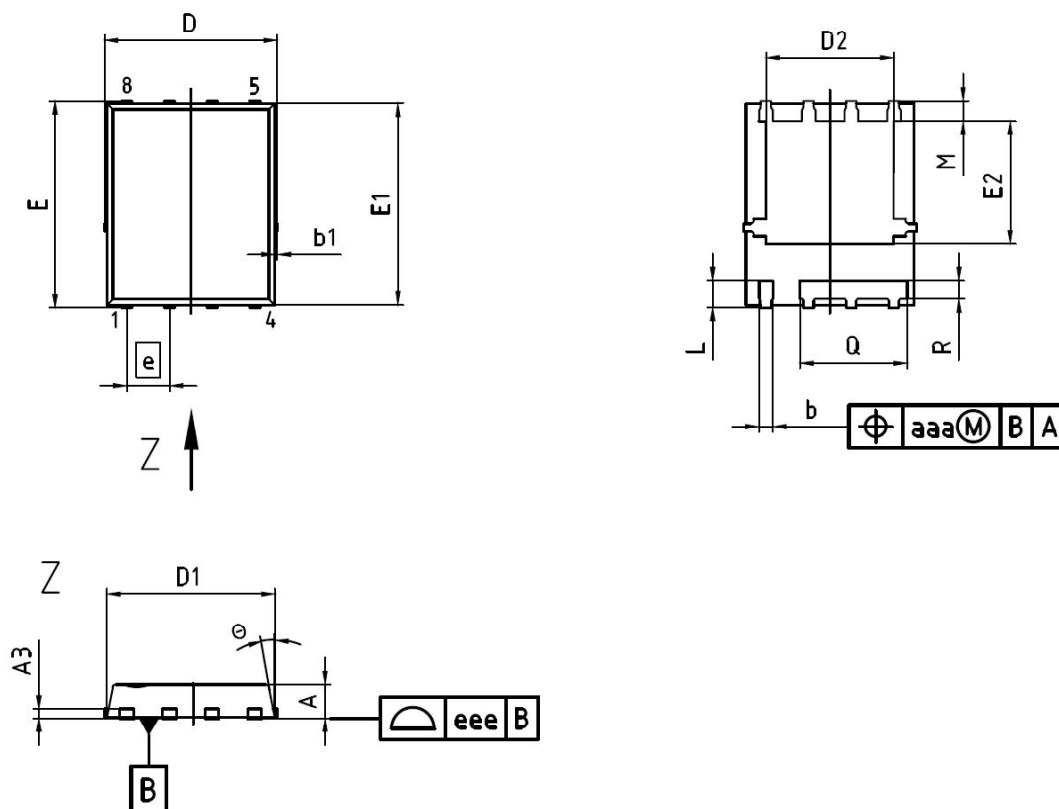


Figure 1 Outline TDSON-8 FL, dimensions in mm/inches

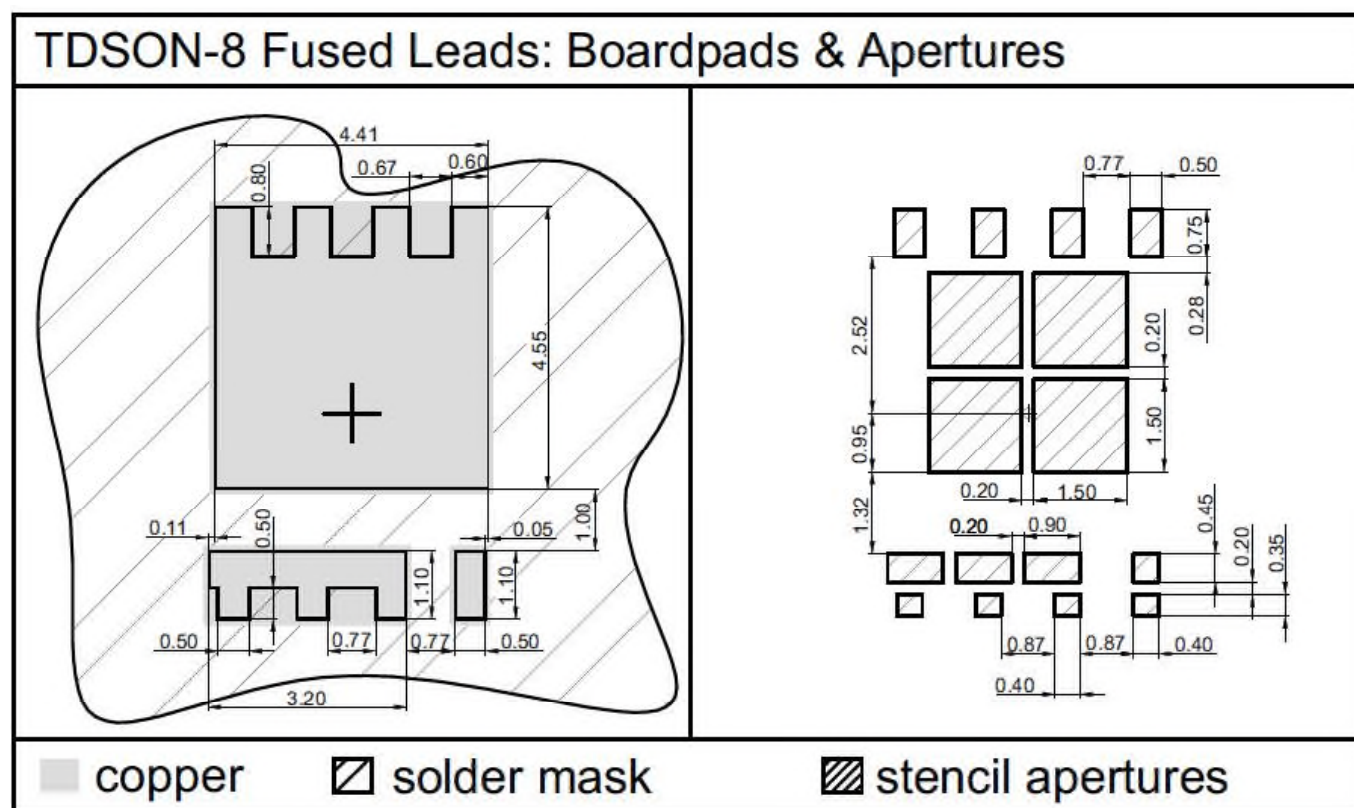


Figure 2 Outline Boardpads (TDSO-8 FL)

Revision History

BSC005N03LS5I

Revision: 2020-04-16, Rev. 2.0

Previous Revision

Revision	Date	Subjects (major changes since last revision)
2.0	2020-04-16	Release of final version

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